

## Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	$I_D$
-60V	8Ω@-10V	-0.17A
	9.9Ω@-4.5V	

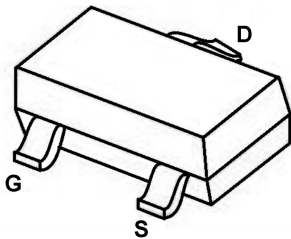
## Feature

- Trench Power LV MOSFET technology
- Low RDS(ON)
- Low Gate Charge
- Suffix "-Q1" for AEC-Q101

## Application

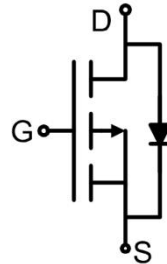
- Video monitor
- Power management

## Package

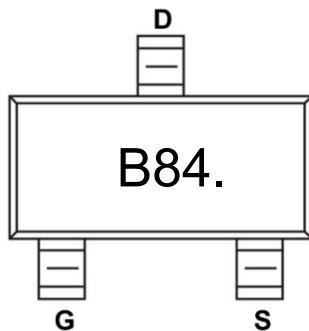


SOT-323

## Circuit diagram



## Marking



### Absolute maximum ratings ( $T_A=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	-60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D$	-0.17	A
Pulsed Drain Current <sup>1)</sup>	$I_{DM}$	-0.68	A
Power Dissipation	$P_D$	0.15	W
Thermal Resistance from Junction to Ambient <sup>2)</sup>	$R_{\theta JA}$	833	$^{\circ}\text{C}/\text{W}$
Junction Temperature	$T_J$	150	$^{\circ}\text{C}$
Storage Temperature	$T_{STG}$	-55 ~ +150	$^{\circ}\text{C}$

### Electrical characteristics ( $T_J=25^{\circ}\text{C}$ , unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}, I_D = -250\mu\text{A}$	-60			V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = -60\text{V}, V_{GS} = 0\text{V}$			-1	$\mu\text{A}$
Gate-body leakage current	$I_{GSS}$	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$			$\pm 100$	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-0.9	-1.4	-2.0	V
Drain-source on-resistance	$R_{DS(on)}$	$V_{GS} = -10\text{V}, I_D = -0.15\text{A}$		3.3	8	$\Omega$
		$V_{GS} = -4.5\text{V}, I_D = -0.15\text{A}$		3.5	9.9	
<b>Dynamic characteristics<sup>3)</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS} = -30\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$		43		pF
Output Capacitance	$C_{oss}$			2.9		
Reverse Transfer Capacitance	$C_{rss}$			1.8		
Total Gate Charge	$Q_g$	$V_{DS} = -30\text{V}, V_{GS} = -10\text{V}, I_D = -0.15\text{A}$		1.77		nC
Gate-Source Charge	$Q_{gs}$			0.57		
Gate-Drain Charge	$Q_{gd}$			0.18		
Reverse Recovery Charge	$Q_{rr}$	$I_F = -0.15\text{A}, di/dt = 100\text{A}/\mu\text{s}$		13		nC
Reverse Recovery Time	$t_{rr}$			23		
Turn-on delay time	$t_{d(on)}$	$V_{GS} = -4.5\text{V}, V_{DD} = -30\text{V}, I_D = -0.15\text{A}, R_{GEN} = 2.5\Omega$		8.6		nS
Turn-on rise time	$t_r$			20		
Turn-off delay time	$t_{d(off)}$			15		
Turn-off fall time	$t_f$			77		
<b>Source-Drain Diode characteristics</b>						
Diode Forward Current	$I_S$				-0.17	A
Diode Forward voltage	$V_{SD}$	$V_{GS} = 0\text{V}, I_S = -0.17\text{A}$			-1.2	V

Notes:

- 1) Pulse Test: Pulse Widths  $\leq 10\mu\text{s}$ , Duty Cycles  $\leq 2\%$ .
- 2) Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.
- 3) Guaranteed by design, not subject to production.

## Typical Characteristics

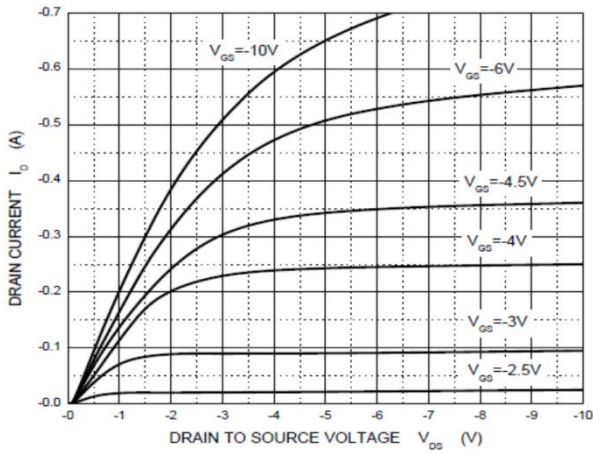


Figure1. Output Characteristics

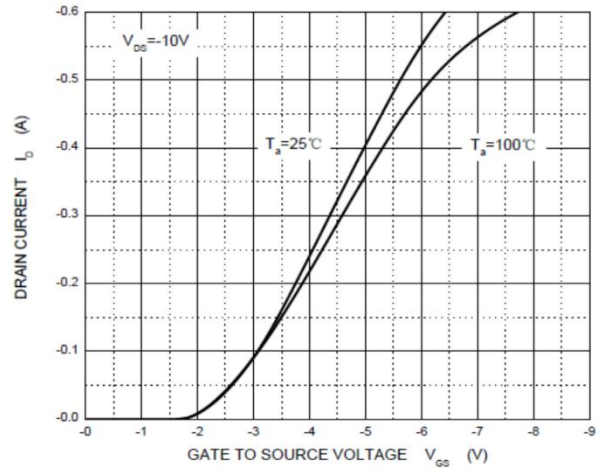


Figure2. Transfer Characteristics

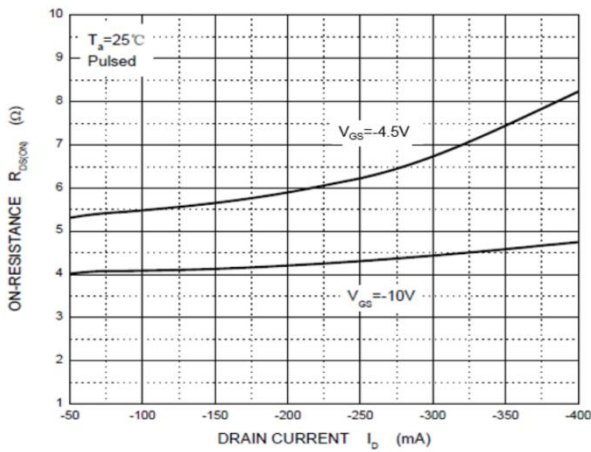


Figure3. Drain-Source on Resistance

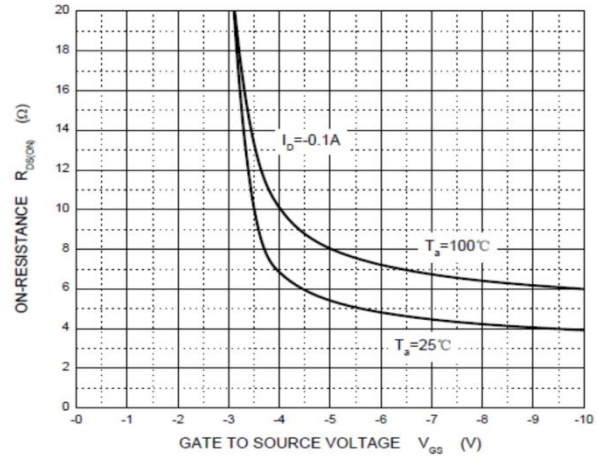


Figure4. Drain-Source on Resistance

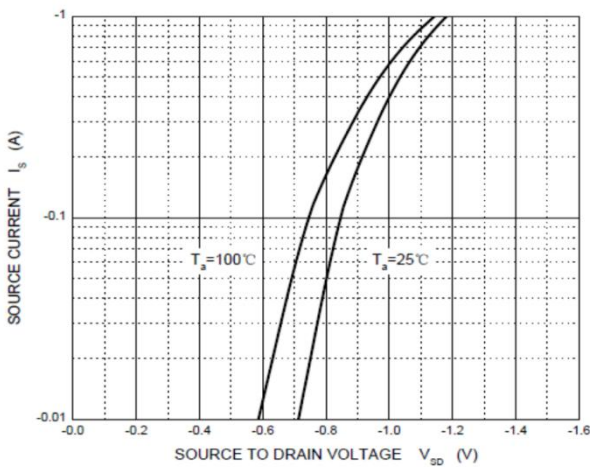


Figure5. Diode Forward Voltage vs. current

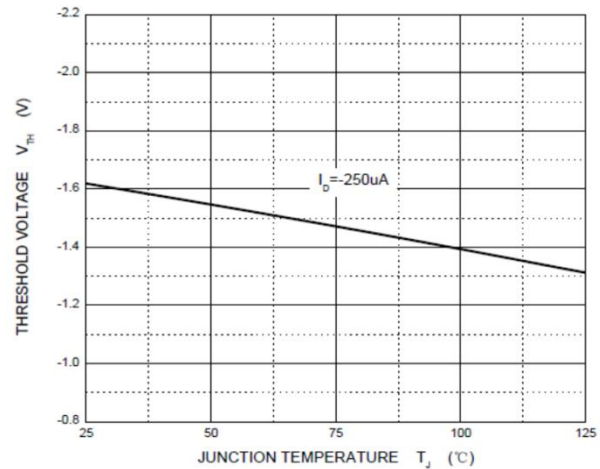


Figure6. Gate Threshold vs. Junction Temperature

## Typical Characteristics

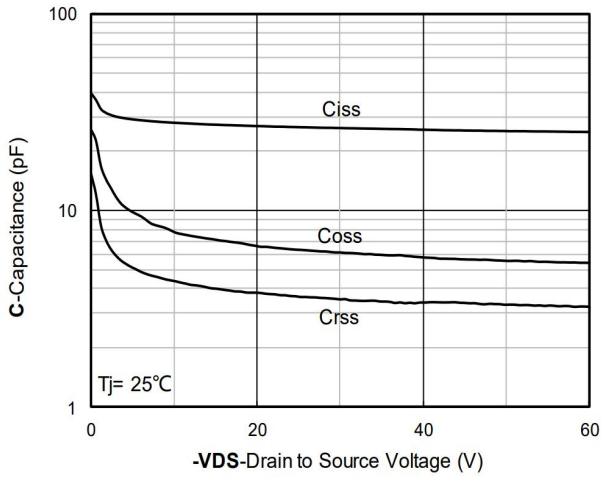


Figure 7. Capacitance Characteristics

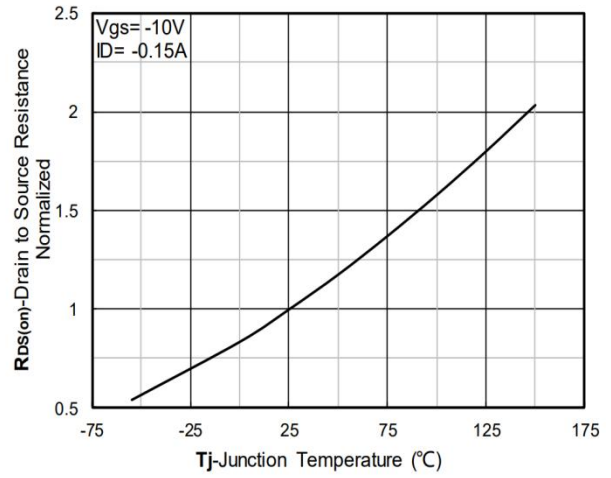
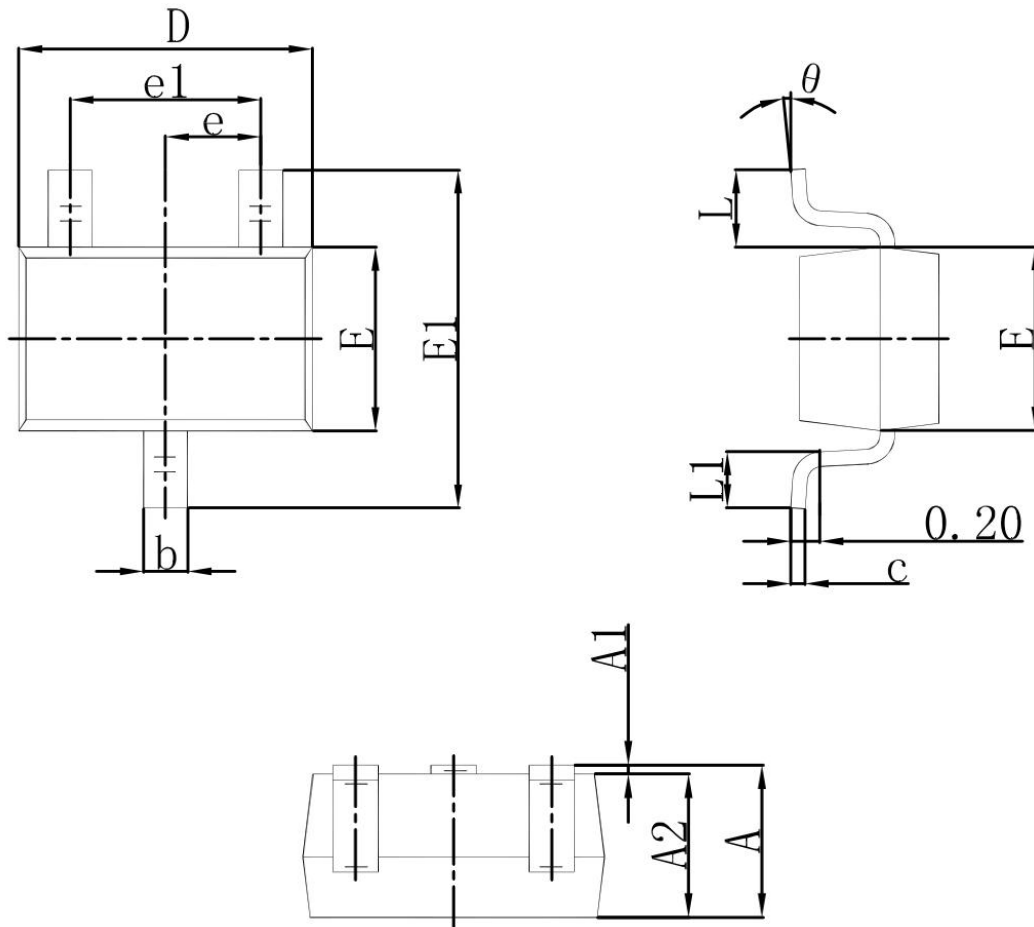


Figure 8. Normalized On-Resistance

### SOT-323 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.150	0.400	0.006	0.016
c	0.080	0.250	0.003	0.016
D	1.800	2.200	0.071	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
e	0.650 TYP.		0.026 TYP.	
e1	1.200	1.400	0.047	0.055
L	0.525 REF.		0.021 REF.	
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°